

DESCRIPTION

The SG3R08B090 GDT offers high surge ratings. Special design features provide high levels of protection against fast rising transients in the 100V/μs to 1kV/μs range usually caused by lightning disturbances. Low insertion loss is perfectly suited to broadband equipment applications. The capacitance does not vary with voltage, and will not cause operational problems with ADSL2+, where capacitance variation across Tip and Ring is undesirable. For AC Power Cross of long duration, over current protection is recommended.

FEATURES

- > Provide ultra-fast response to surge voltage from slow-rising.
- > Stable breakdown voltage.
- > High insulation resistance.
- > surge of 100V/s to rapid-rising surge of 1KV/μs.
- > Low capacitance(≤2pF).
- > High holdover voltage.
- > Large absorbing transient current capability.
- > Micro-Gap Design.
- > Size: φ8.0x10.0mm.

APPLICATIONS

- > Communication equipment.
- > Repeaters, Modems.
- > Telephone Interface, Line cards.
- > Data communication equipment.

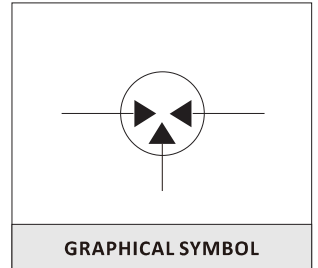
PART NUMBER CODE

S G 3R08 B 090

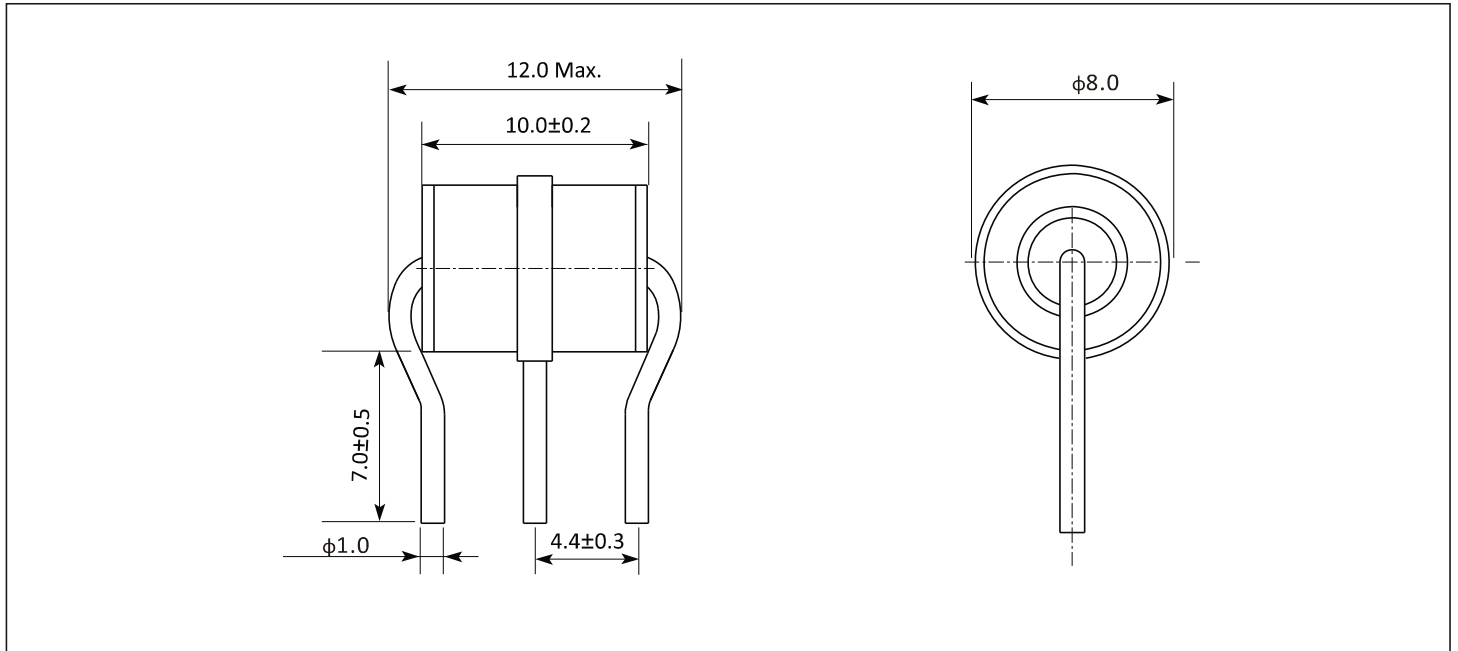
- DC Breakdown Voltage: 090=90V
- Polar: B=Bidirectional, U=Unidirectional
- Product Size: 3R08=φ8.0x10.0mm
- Product Line: G=Gas Discharge Tube
- Semiware Brand

ELECTRICAL CHARACTERISTIC

Part Number	DC Breakdown Voltage	Tolerance of Vs	Impulse Spark-over Voltage	Impulse Discharge Current	Insulation Resistance		C@1MHZ Max.
	100V/s				Min.	DC	
SG3R08B090	90V	±20%	700V	10KA	1Gohm	50V	2.0pF



PRODUCT DIMENSIONS



ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing Items	Technical Standards
High Temperature Storage Test	Temperature:85°C; Time: 2H
Low Temperature Storage Test	Temperature:-40°C; Time: 2H
Vibration	Frequency:10-500Hz;Amplitude:0.15mm;Time:45min
Resistance of Soldering Heat	Temperature:260°C ;Time of dip soldering:10s,1time

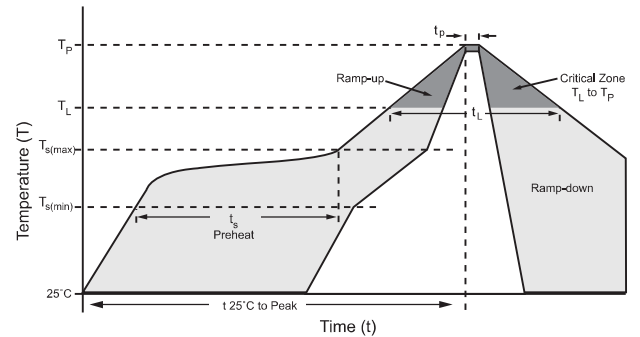
SOLDERABILITY TEST

Solderability	Solder Pot Temperature	245±5°C
	Solder Dwell Time	4~6 seconds



REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min (Ts(min))	150°C
	Temperature Max (Ts(max))	200°C
	Time (min to max) (ts)	60–180 secs
Average ramp up rate (Liquidus Temp (TL) to peak)		3°C/second max
Ts(max) to TL - Ramp-up Rate		3°C/second max
Reflow	Temperature (TL) (Liquidus)	217°C
	Time (min to max) (ts)	60–150 seconds
Peak Temperature (Tp)		260°C
Time within 5°C of actual peak Temperature (tp)		10-30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (Tp)		8 minutes Max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	SIZE(mm)	QTY	PACKING OPTION
SG3R08B090	φ8.0x10.0	100PCS	Blister Box

